

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently amended) A circuit substrate comprising:
an insulating base;
wiring layers disposed on said insulating base;
a conductor disposed in said insulating base to electrically connect between said wiring layers in an interlayer of said insulating base; and
a region containing an uncured resin component provided at a bonding site between said wiring layers and said insulating base adjacent said conductor,
wherein a bonding strength between said wiring layers and said conductor is greater than a bonding strength between said wiring layers and said insulating base, and
wherein said conductor contains a resin composition, and a glass transition temperature of the resin composition is set lower than a glass transition temperature of a resin composition contained in said insulating base.
2. (Cancelled)
3. (Previously presented) The circuit substrate according to claim 1, wherein said insulating base and said conductor contain a thermosetting epoxy resin composition, and a volume content of the thermosetting epoxy resin in said conductor is set larger than a volume content of the thermosetting epoxy resin in said insulating base.
4. (Previously presented) The circuit substrate according to claim 1, wherein the bonding strength between said wiring layers and said conductor is greater than the bonding strength between said wiring layers and said insulating base in an area of the wiring layer adjacent said conductor.

5. (Previously presented) The circuit substrate according to claim 1, wherein a metal cohesion is applied between said conductor and said wiring layers.

6. (Previously presented) The circuit substrate according to claim 1, wherein a non-bonding region is provided between said wiring layers and said insulating base adjacent said conductor.

7. (Cancelled)

8. (Previously presented) The circuit substrate according to claim 1, wherein a surface irregularity is formed at a bonding site between said conductor and said wiring layers.

9. (Currently amended) A circuit substrate comprising:

an insulating base; ~~and~~

a conductor provided in said insulating base to electrically connect an interlayer of said insulating base; and [[,]]

a region containing an uncured resin component provided at a bonding site between wiring layers and said insulating base adjacent said conductor,

wherein a tensile strength of said conductor is greater than a bonding strength between said conductor and said insulating base on a wall surface of said conductor, and

wherein said conductor contains a resin composition, and a glass transition temperature of the resin composition is set lower than a glass transition temperature of a resin composition contained in said insulating base.

10-12. (Cancelled)

13. (Previously presented) The circuit substrate according to claim 1, wherein said region has a conductor and an uncured resin included in the conductor.

14. (New) A circuit substrate comprising:

an insulating base;
wiring layers disposed on said insulating base; and
a conductor disposed in said insulating base to electrically connect between said wiring layers in an interlayer of said insulating base,
wherein a bonding strength between said wiring layers and said conductor is relatively greater than a bonding strength between said wiring layers and said insulating base, and
wherein said conductor contains a resin composition, and a glass transition temperature of the resin composition is set lower than a glass transition temperature of a resin composition contained in said insulating base.

15. (New) A circuit substrate comprising:

an insulating base; and
a conductor disposed in said insulating base to electrically connect an interlayer of said insulating base,
wherein a tensile strength of said conductor in a base thickness direction is relatively greater than a bonding strength between said conductor and said insulating base on a wall surface of said conductor, and
wherein said conductor contains a resin composition, and a glass transition temperature of the resin composition is set lower than a glass transition temperature of a resin composition contained in said insulating base.